BGF104

HSMMC Interface Filter and ESD Protection

AIM
Discrete Semiconductors



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BGF104 Data sheet

Revision History: 2005-06-07

Previous Version: 2005-02-07

Page Subjects (major changes since last revision)

4, 7 Package size reduced

5 Resistor numbers changed to match to schematic

all Preliminary status of data sheet removed

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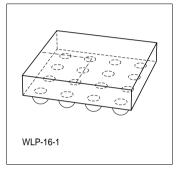


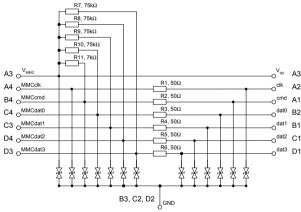
HSMMC Interface Filter and ESD Protection

BGF104

Features

- ESD protection and filter for High Speed Multi Media Card interface
- ESD protection up to 15 kV
- 16 pin green wafer level package with SnAgCu solder balls
- 500 µm solder ball pitch
- · 300 µm solder ball diameter





Description

The BGF104 is an ESD protection and filter circuit for a high speed multi media card interface. External pins are protected up to 15 kV contact discharge according to IEC61000-4-2. The wafer level package is a green package with a size of only 1.96 mm x 1.96 mm and a total height of 0.65 mm.

Туре	Package	Marking	Chip
BGF104	WLP-16-1	BGF104	N0708



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Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage at all pins to GND	V_P	14	V
Operating temperature range	T _{OP}	-40 +85	°C
Storage temperature range	T _{STG}	-65 +150	°C
Contact discharge according to IEC61000-4-2 Pins A4, B4, C3, C4, D3, D4	V _{ESD}	2	kV
Contact discharge according to IEC61000-4-2 Pins A1, A2, A3, B1, B2, C1, D1	V _{ESD}	15	kV

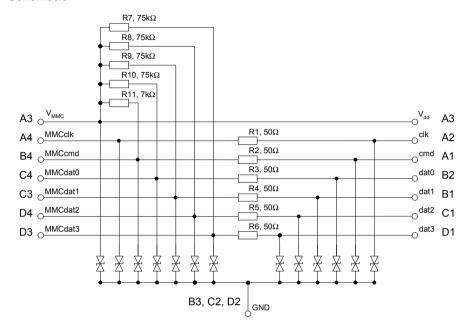
Electrical Characteristics at T_A =25°C

Parameter	Symbol	min.	typ.	max.	Unit
Resistors					
$R_1 \dots R_6$	R ₁₆	40	50	60	Ω
R ₇ R ₁₀	R ₇₁₀	52.5	75	97.5	$k\Omega$
R ₁₁	R ₁₁	4.9	7	9.1	kΩ
Reverse current of ESD protection diodes					
$V_R = 3V$	I_R		5	100	nA
$V_R = 14V$			0.1	10	μΑ
Line capacitance Capacitance of each line to GND ¹⁾					pF
$V_R = 0 V$	C_T		16	20	

 $^{^{1)}}$ Without line coupling by resistors R_7 - R_{11}

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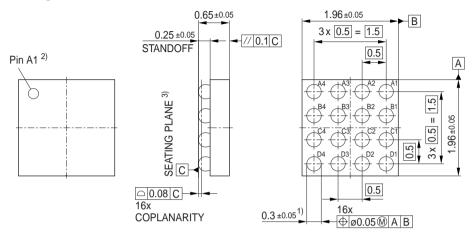
Schematic





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Package Outline



- 1) Dimension is measured at the maximum solder ball diameter, parallel to primary datum C
- 2) Pin A1 corner identified by marking
- 3) Primary datum C and seating plane are defined by the spherical crowns of the balls

GWLN1057

WLP-16-1